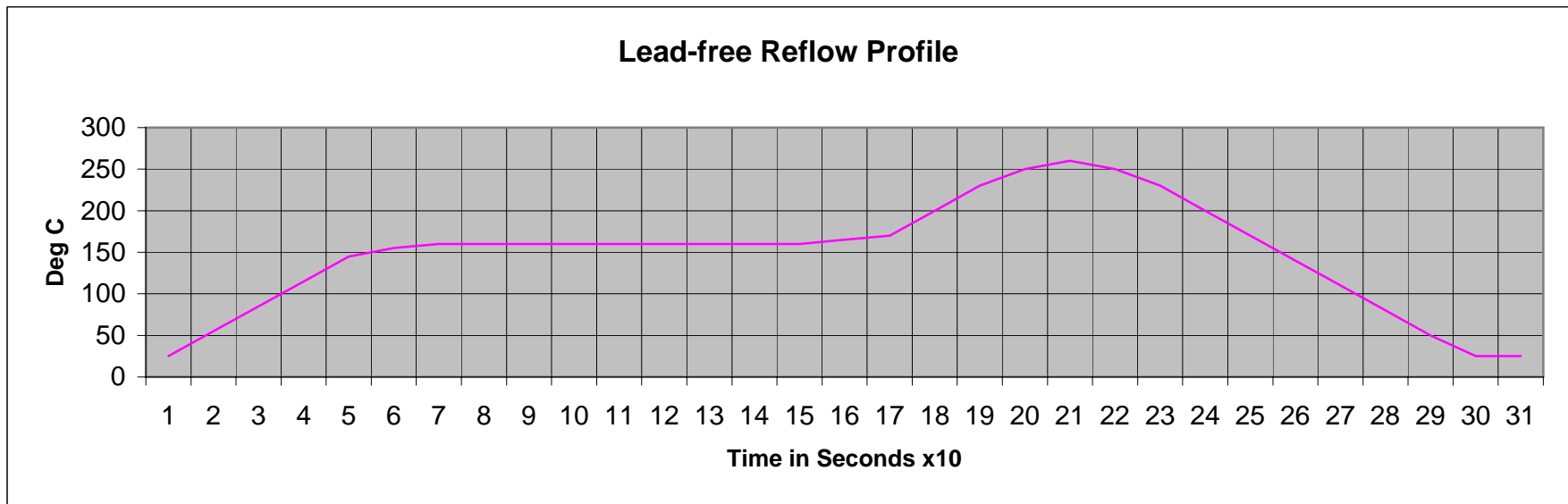




## Lead-free Package Reflow Profile

Required Parameters	Specs
Average ramp-up rate	3 C / sec max
Pre Heat Temp 150-200° C	60 - 180 sec
Temp > 217° C	60 - 150 sec
Time @ Peak Temperature	20 -40 secs
Peak Temperature	260° +0° / -5° C
Ramp-down Rate	-6 C / sec max
Time 25° C to Peak Temp.	8 minutes max



The Reflow Profile is used for pre-conditioning and moisture sensitivity classification of Micrel SMD ( Surface Mount Devices).

Post moisture soak, SMD devices are exposed to 3X cycles.

Temperatures refer to top side of the package, measured on the package body surface.

